**AGENDA, EUROPEAN IBIS SUMMIT MEETING**

Wednesday, May 13, 2015

Seminaris Campus Hotel Berlin/ Dahlem Cube

Takustraße 39, 14195

Berlin, Germany

Room: Cambridge (Check at Entrance)

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**13:00 SIGN IN**

**13:15 WELCOME AND INTRODUCTIONS**

Randy WOLFF, Micron Technology, IBIS Secretary, USA

**13:30 Physics and Modeling of Vias in Printed Circuit Boards**

Jan PREIBISCH and Christian SCHUSTER,

Technische Universitat Hamburg-Harburg, Germany

[Presented by Jan PREIBISCH]

**14:30 Chair's Status Report**

Michael MIRMAK, Intel Corporation USA

[Presented by Randy WOLFF, Micron Technology, USA]

**15:00 IBIS Model Formulation and Extraction for SPI Evaluation**

Wael DGHAIS, Kevin F.G. PINTO, and Jonathan RODRIGUEZ;

University of Aveiro, Institute of Telecommunications,

Portugal

[Presented by Wael DGHAIS]

**15:30 BREAK (15 Minutes)**

**15:45 [Define Package Model] Proposed Extension**

Randy WOLFF\*, Radek BIERNACKI\*\*, and Bob ROSS\*\*\*,

\*Micron Technology, \*\*Keysight Technology, and

\*\*\*Teraspeed Labs, USA

[Presented by Randy WOLFF]

**16:15 Interconnect Task Group Update - Package Modeling**

Randy WOLFF, Micron Technology, USA

**16:45 Time Response Utility**

Bob ROSS, Teraspeed Labs, USA

[Presented by Anders EKHOLM, Ericsson, Sweden]

**17:15 DISCUSSION AND CLOSING REMARKS**

Randy WOLFF, Micron Technology, USA

**18:00 END OF MEETING**